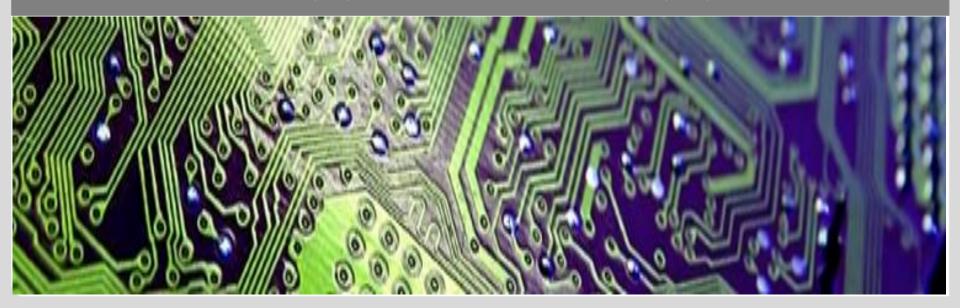


Architectural Aspects in Design and Analysis of SOTbased Memories

Rajendra Bishnoi, Mojtaba Ebrahimi, Fabian Oboril & Mehdi Tahoori

INSTITUTE OF COMPUTER ENGINEERING (ITEC) – CHAIR FOR DEPENDABLE NANO COMPUTING (CDNC)



Outline



Motivation

SOT based MRAM

- STT-MRAM & Limitations
- Basics of SOT-MRAM
- Simulation tool flow

Results

- For various memory technologies
- System-level

Summary & Conclusion

Outline

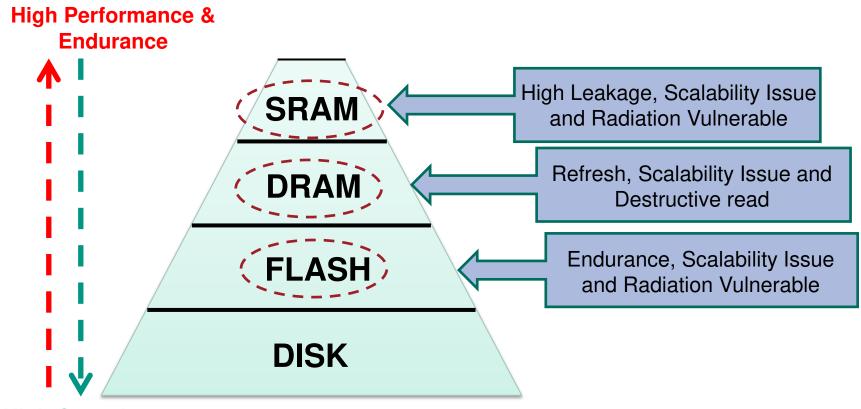


Motivation

- SOT based MRAM
 - STT-MRAM & Limitations
 - Basics of SOT-MRAM
 - Simulation tool flow
- Results
 - For various memory technologies
 - System-level
- Summary & Conclusion

Memory Hierarchy

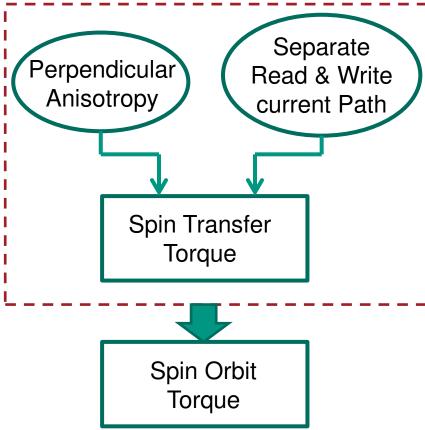




- **High Capacity**
- A Universal Memory Required to overcome these limitations
- Non Volatile Magnetic RAM is promising candidate

Motivation





STT-MRAM has potential to become universal memory technology

- However, obstacles are
 - High write current & time
 - "Read Disturb"
- Addressed using Spin Orbit Torque (SOT)

Results in

- Low Write Current
- Low Switching Time
- Avoid Read Disturb

Outline



Motivation

SOT based MRAM

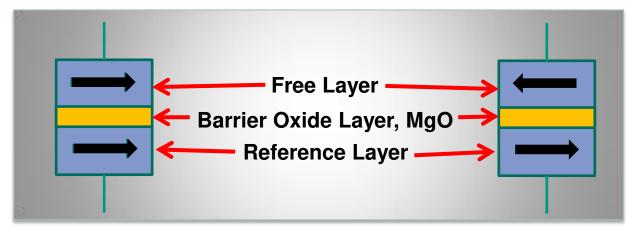
- STT-MRAM & Limitations
- Basics of SOT-MRAM
- Simulation tool flow

Results

- For various memory technologies
- System-level
- Summary & Conclusion

Basics of Spin Transfer Torque (STT)





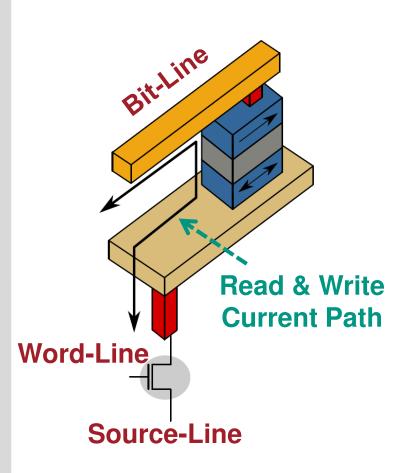
Parallel Magnetisation (P)
Low Resistance

Anti- Parallel Magnetisation (AP)
High Resistance

- Two ferromagnetic layers seperated by a oxide barrier layer
- Magnetic Tunneling Junction (MTJ) Cell is a storing device
- Value stored as a resistance state

Bit-cell using STT based MTJ cell





- Bit-cell has three terminals:
 - Bit-Line
 - Word-Line
 - Source-Line
- Read current is unidirectional
- Write current is bidirectional
- Possible "Read Disturb"
 - Same path for read and write

Merits & Demerits of STT



- Merits:
 - High Density
 - Non-Volatility
 - Scalability
 - CMOS Compability

- Low Read Latency
- High Endurance
- High Retention
- Radiation Immune

- Demerits:
 - High Write Power
 - High Write Latency

- Aditional Layer requires
- Read Disturb

In-Plane Vs Perpendicular Anisotropy



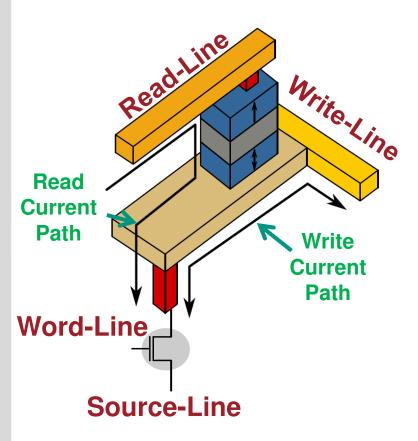
Parameters	In-Plane Magnetic Anisotropy	Perpendicular Magnetic Anisotropy				
Diagram		1				
Ratio of critical switching current to thermal stability, $\frac{I_C}{\Delta}$	$\frac{\alpha}{\eta} \times \left(1 + \frac{H_d}{2H_k}\right)$ where, α = damping constant, η =STT efficiency, H_d = demagnetization field, H_k =in-plane anisotropy field	$\frac{lpha}{\eta}$				
switching current	High	Low				
switching time	More	Less				
Perpendicular magnetic anisotropy						

"Read Disturb" still remains challenge

Low switching current Less switching time

Spin Orbit Torque





- Separate read and write current paths
 - One additional terminal
 - No read disturb
 - Need not to maintain ratio of I_{Read}/I_{Write}
- Less current required to flip due to parallel magnetization
- Fast switching

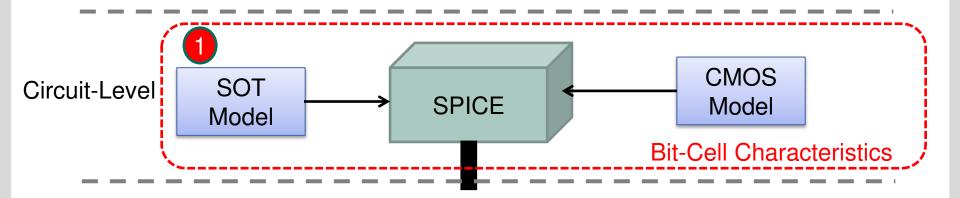
STT-MRAM VS SOT-MRAM



Parameter	STT-MRAM	SOT-MRAM	
Bit-cell Terminals (1T1MTJ type)	3	4	
Access Transistor	8F	2F	
Current (uA)	750	100	
Write Current Period (ns)	11	0.3	
Read Disturb	High Probability	Almost Nil	
Read Energy (pJ)	1.8	1.8	
Write Energy (pJ)	3.9 (reset)/3.4(set)	0.1	
Switching Behavior	Asymmetrical	Almost Symmetrical	
Magnetic Anisotropy	In-Plane	Perpendicular	

Tool Simulation Flow

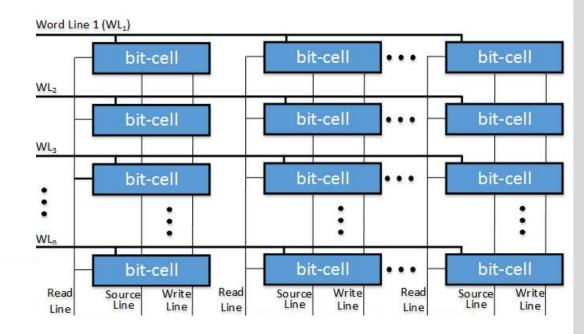




Basic Memory Architecture



- Word-line driv the access transistor of bitcell
- Write Enable =1, for write operation
- Write Enable =0, for read operation



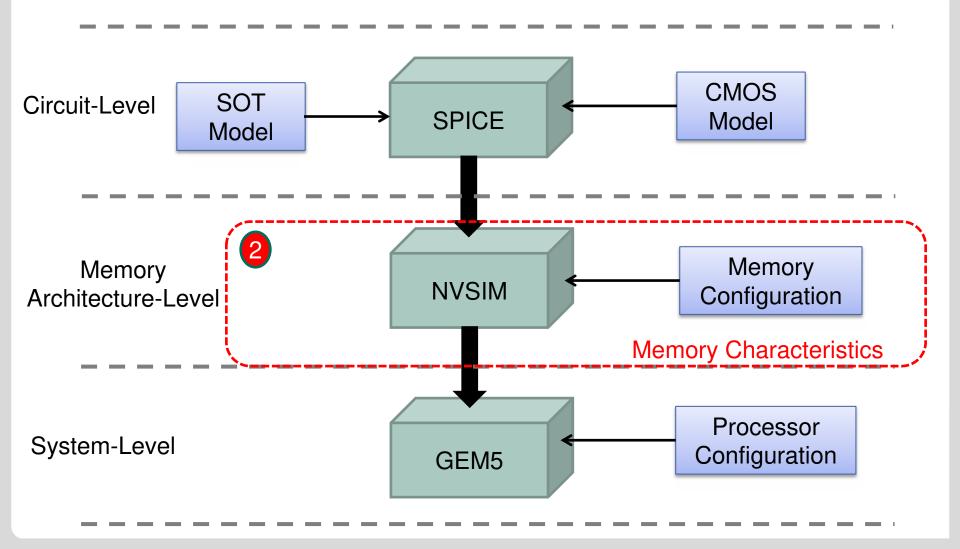
Simulation models

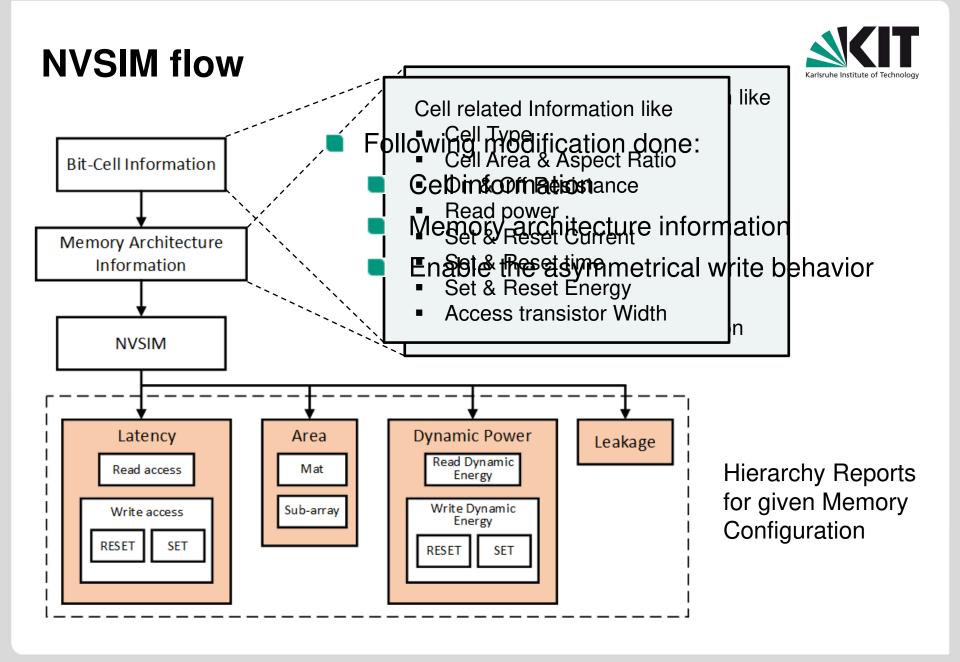


- STT-MTJ
 - SPICE modelling framework presented in [W. Guo, JAP-2010]
- SOT-MTJ
 - Compact Verilog-A framework presented in [K. Jabeur, IJESE-2013]
- CMOS
 - General purpose TSMC 65nm models.

Tool Simulation Flow

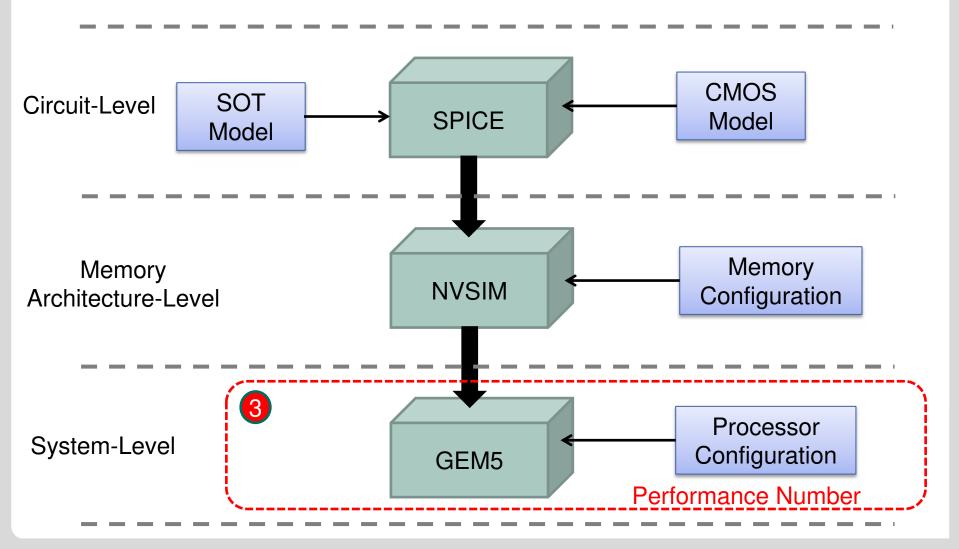






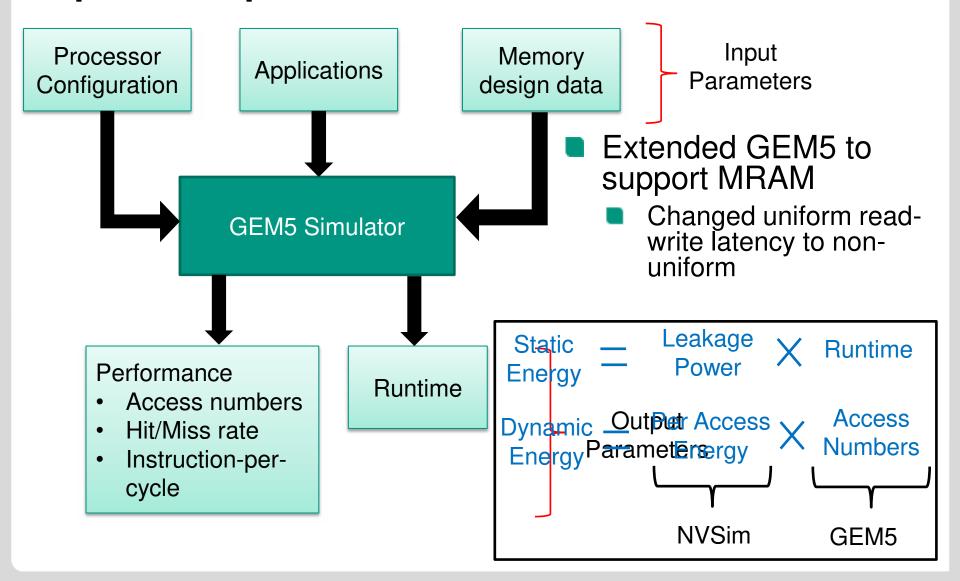
Tool Simulation Flow





Input & Output Parameters





Outline



Motivation

SOT based MRAM

- STT-MRAM & Limitations
- Basics of SOT-MRAM
- Simulation tool flow

Results

- For various memory technologies
- System-level
- Summary & Conclusion

Comparison of various Memory Technologies

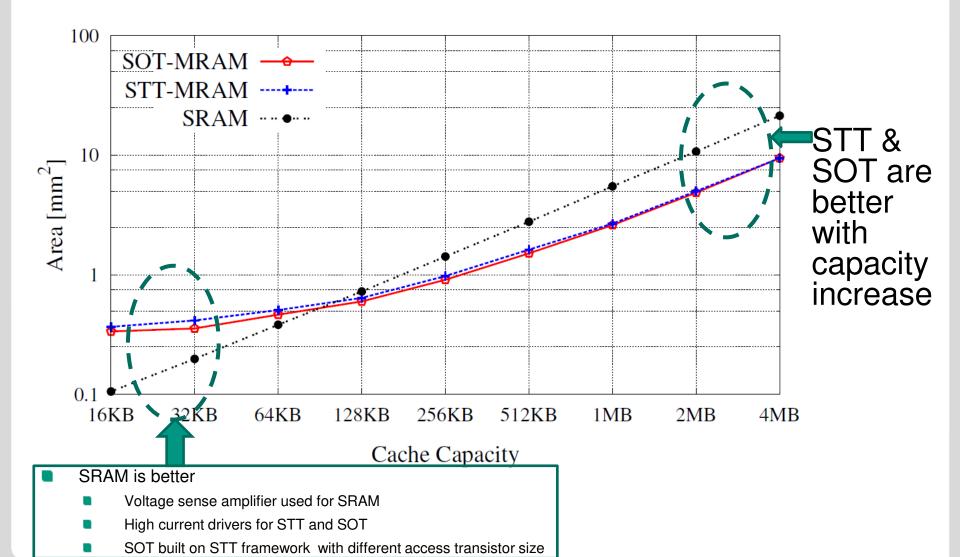


Parameters	SRAM	NAND FLASH	STT- MRAM	SOT- MRAM	PC- RAM	R- RAM
Area [mm²]	2.8	0.2	1.6	1.5	0.3	0.7
Read Latency [ns]	2.2	565	1.2	1.13	0.6	1.2
Write Latency [ns]	2.0	2×10^{5}	11.2	1.4	150	21
Read Energy [pJ]	587	3921	260	247	363	193
Write Energy [pJ]	355	6902	2337	334	63670	592
Leakage [mW]	932	77	387	254	153	115

- Values are extracted using NVSim for
 - 512 Kbyte capacity
 - Latency optimization

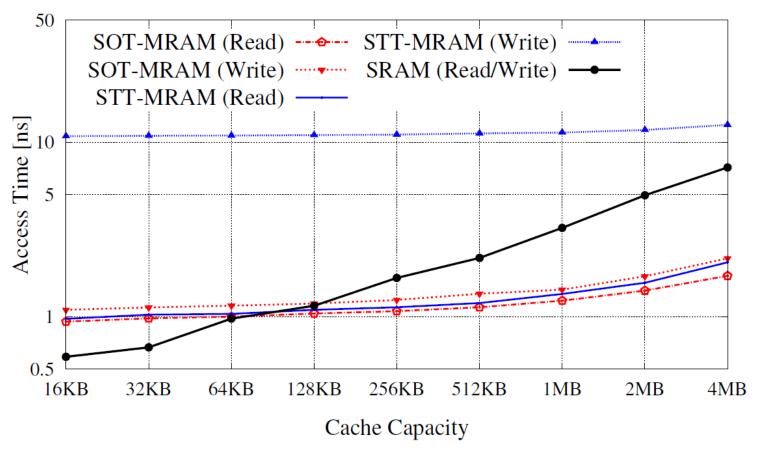
Area Comparison for various memory sizes





Read & Write Latency Comparison

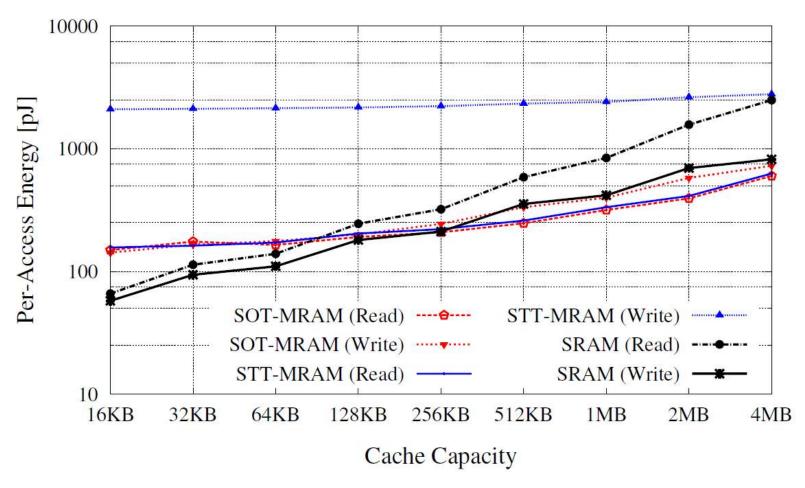




- SRAM varies linearly with capacity increase
- STT & SOT, remain almost flat with capacity increase

Energy Comparison

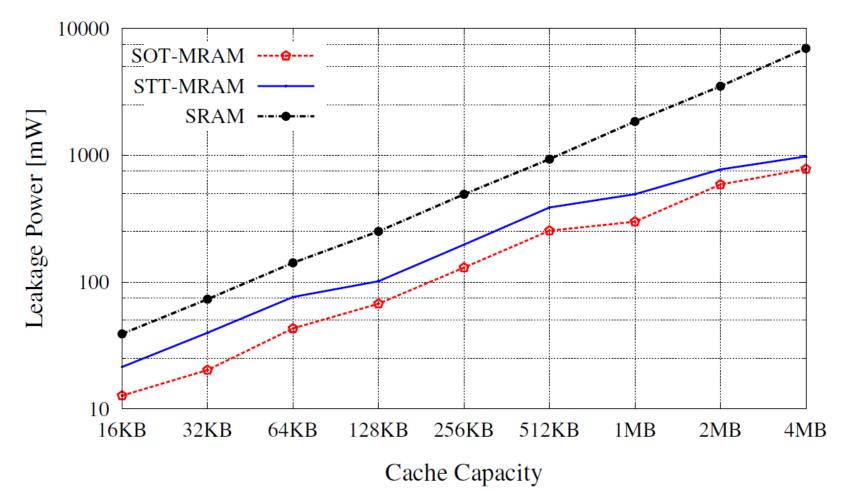




SOT has almost same read & write access energy

Leakage Comparisons





- SRAM varies linearly with capacity increase
- STT & SOT, leakage is due to periphery circuits

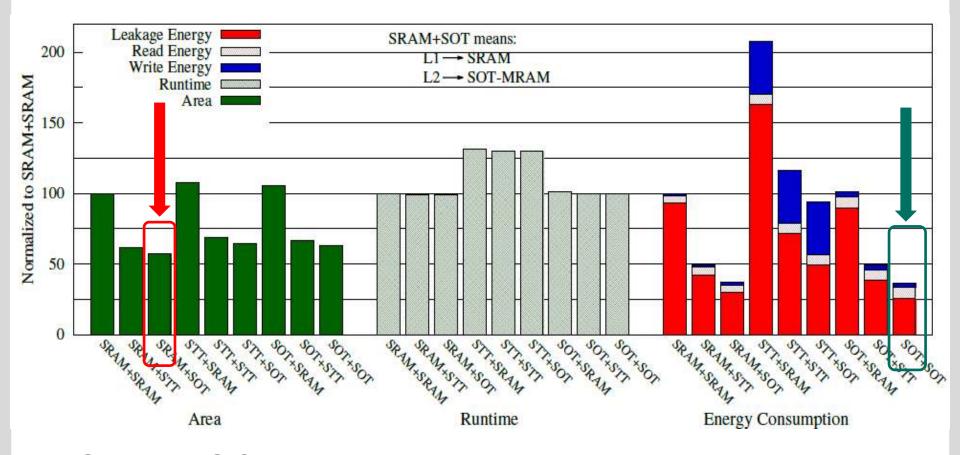
System-Level Evaluation



- Configuration details for Experiments:
 - Processor : single core, 3 GHz
 - L1-Cache: 32 Kbyte with 64B Data Width
 - L2-Cache: 512 Kbyte with 64B Data Width
- Application (MiBench):
 - BasicMath, BitCnt, Qsort, Dijkstra, Patricia, StrSearch, SHA, CRC, FFT

Comparisons with Various Cache conf.





- SRAM+SOT is best area combination.
- SOT+SOT is best energy configuration

Benchmark Analysis



			,;					
	Runtime [ms]			Energy [mJ]				
	SRAM+SRAM	SRAM+STT	SRAM+SOT	SOT+SOT	SRAM+SRAM	SRAM+STT	SRAM+SOT	SOT+SOT
BasicMath	61.4	59.8	59.8	60.5	66.4	31.6	23.6	22.8
BitCount	130.1	130.1	130.1	130.1	133.8	63.0	45.6	40.4
CRC	998.8	998.8	998.8	1025.5	1075	531.5	398.1	395.7
Dijkstra	62.7	62.4	62.4	62.6	75.5	41.2	32.9	36.8
FFT	176.1	175.4	175.3	176.1	191.9	95.5	72	71.6
Patricia	49.1	46.7	46.7	47.6	54.6	25.8	19.5	19.4
QSort	35.2	34.9	34.9	34.9	36.7	17.6	12.7	11.6
SHA	23.3	23.3	23.3	23.3	26.1	13.4	10.3	10.7
StringSearch	1.5	1.5	1.5	1.5	1.7	0.9	0.7	0.7
Average	170.9 (100 %)	170.0 (99 %)	170.0 (99 %)	173.3 (101%)	184.6 (100 %)	91.2 (49 %)	68.4 (37 %)	67.7 (36 %)
77.79	*	,		1111	1	25	<u> </u>	L

- SOT only solution is best for low power.
- For runtime, the best combination is SRAM+SOT.

Outline



Motivation

SOT based MRAM

- STT-MRAM & Limitations
- Basics of SOT-MRAM
- Simulation tool flow

Results

- For various memory technologies
- System-level

Summary & Conclusion

Summary & Conclusion



- Developed hybrid memory architecture based on SOT-MRAM
 - A cell-level information is extracted using SPICE simulations
 - NVSim tool is explored to estimate the design data
 - Many applications run using GEM5 simulator
- SOT is the best solution for low power
- Overall best is hybrid memory architecture SRAM+SOT